

Takafumi Fukushima

List of Publications by Year in descending order

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#	ARTICLE	IF	CITATIONS
1	Flexible Hybrid Electronics Technology Using Die-First FOWLP for High-Performance and Scalable Heterogeneous System Integration. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 1738-1746.	1.4	32
2	Oxide-Oxide Thermocompression Direct Bonding Technologies with Capillary Self-Assembly for Multichip-to-Wafer Heterogeneous 3D System Integration. Micromachines, 2016, 7, 184.	1.4	17
3	Development of Eccentric Spin Coating of Polymer Liner for Low-Temperature TSV Technology With Ultra-Fine Diameter. IEEE Electron Device Letters, 2019, 40, 95-98.	2.2	14
4	Self-Assembly and Electrostatic Carrier Technology for Via-Last TSV Formation Using Transfer Stacking-Based Chip-to-Wafer 3-D Integration. IEEE Transactions on Electron Devices, 2017, 64, 5065-5072.	1.6	11
5	Investigation of TSV Liner Interface With Multiwell Structured TSV to Suppress Noise Propagation in Mixed-Signal 3D-IC. IEEE Journal of the Electron Devices Society, 2019, 7, 1225-1231.	1.2	6
6	3-D Sidewall Interconnect Formation Climbing Over Self-Assembled KGDs for Large-Area Heterogeneous Integration. IEEE Transactions on Electron Devices, 2017, 64, 2912-2918.	1.6	5
7	High-Thermoresistant Temporary Bonding Technology for Multichip-to-Wafer 3-D Integration With Via-Last TSVs. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 181-188.	1.4	5
8	Significant Die-Shift Reduction and $\frac{1}{4}$ LED Integration Based on Die-First Fan-Out Wafer-Level Packaging for Flexible Hybrid Electronics. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 1419-1422.	1.4	5
9	On-wafer thermomechanical characterization of a thin film polyimide formed by vapor deposition polymerization for through-silicon via applications: Comparison to plasma-enhanced chemical vapor deposition SiO_2 . Journal of Polymer Science, 2020, 58, 2248-2258.	2.0	5